Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ***: Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2016-04-12
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Floriana San Biagio	**Representative Title**	AMG Material Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

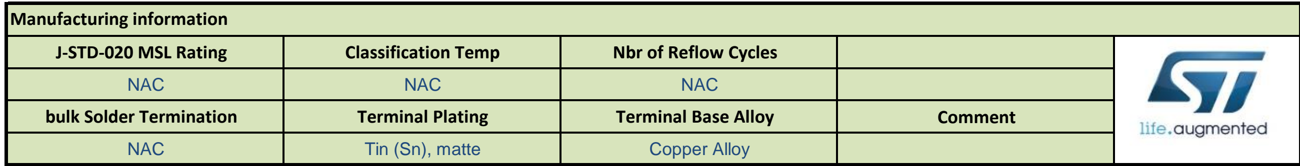
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	9M8W*L289EA6	A	Z8GA	2016-04-12
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	480.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
DIP	9.05X6.4X3.32	10	Through-hole	
Comment	Package: 8W PDIP 08 .3 CU .25 Au W.; MDF valid for UC2844BN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false

Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	9M8W*L289EA6					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other Inorganic Material	3.181	mg	Supplier	Silicon die	Silicon (Si)	7440-21-3		3.088	mg	970764	6433
				supplier	metallization	Aluminium (Al)	7429-90-5		0.038	mg	11946	79
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.013	mg	4087	27
				supplier	passivation	Silicon Oxide(SiO_2)	7631-86-9		0.019	mg	5973	40
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	629	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.021	mg	6602	44
Leadframe	Copper and its alloy	184.682	mg	Supplier	Alloy	Copper(CU)	7440-50-8		179.288	mg	970793	373517
				Supplier	Alloy	Iron (Fe)	7439-89-6		3.864	mg	20922	8050
				Supplier	Alloy	Iron Phosphide (Fe_2P)	1310-43-6		0.028	mg	152	58
				Supplier	Alloy	Zinc (Zn)	7440-66-6		0.093	mg	504	194
				Supplier	Alloy	Silver(Ag)	7440-22-4		1.409	mg	7629	2935
Die Attach	Other Organic Material	0.571	mg	Supplier	Glue	Silver(Ag)	7440-22-4		0.408	mg	714536	850
				Supplier	Glue	Epoxy Resin	Proprietary		0.086	mg	150613	179
				Supplier	Glue	Epoxy Resin	Proprietary		0.043	mg	75306	90
				Supplier	Glue	Epoxy resin modifier	Proprietary		0.017	mg	29772	35
				Supplier	Glue	Amine	Proprietary		0.017	mg	29772	35
Bonding wire	Other Inorganic Material	0.081	mg	Supplier	Bonding wire	Copper(CU)	7440-50-8		0.081	mg	1000000	169
Encapsulation	Other Organic Material	289.059	mg	Supplier	Molding compound	Silica Fused	60676-86-0		231.249	mg	800006	481769
				Supplier	Molding compound	Epoxy Resin	Proprietary		28.905	mg	99997	60219
			mg	Supplier	Molding compound	Phenol Resin	Proprietary		18.788	mg	64997	39142
			mg	Supplier	Molding compound	Carbon Black	1333-86-4		10.117	mg	35000	21077
Finishing	Other Inorganic Material	2.426	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		2.426	mg	1000000	5054